Build Up HDI (Standard)

HDI10_2+6(8b)+2_1,00_17.5_engl

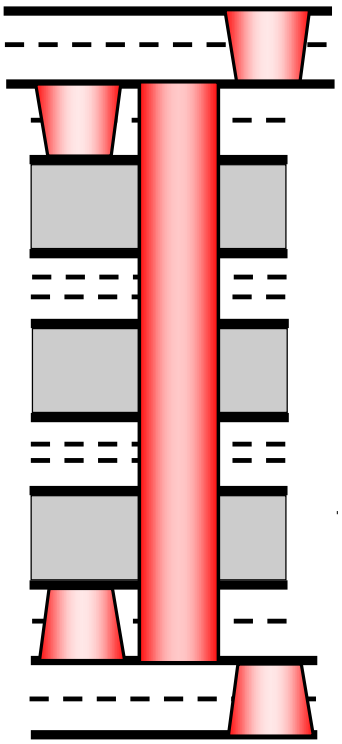
10 - Layers

Core: 0,10 mm Cu 17.5/17.5 µm

WE-Articel No.: | **2 + 6(8B) + 2**

Customer:

WÜRTH ELEKTRONIK



layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	60	
	2		Foil	12 µm		35	
					1 x 1080	66	
	3			17.5 µm		16	
			0,100 mm			100	
	4			17.5 µm		16	
					2 x 1080	134	
	5			17.5 µm		16	
			0,100 mm			100	
	6			17.5 µm		16	
					2 x 1080	134	
	7			17.5 µm		16	
			0,100 mm			100	
	8			17.5 µm		16	
					1 x 1080	66	
	9		Foil	12 µm		35	
					1 x 1080	60	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1010

Note: Lamination thickness for Prepregs depending on layout characteristics.

							Date:	Engineer:
final lamination thickness:	**1,00**	+/-	0,08	mm				
thickness with electro plated Cu:	1,09	+/-	0,11	mm				
total thickness with soldermask	1,15	+/-	0,13	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision	page:
27.03.2006	**S. Keller**	04.05.2006	M.Kress	04.05.2006	R.Schönholz	00	18+